

BFP420

NPN Silicon RF Transistor

- For high gain low noise amplifiers
- For oscillators up to 10 GHz
- Noise figure F = 1.1 dB at 1.8 GHz outstanding G_{ms} = 21 dB at 1.8 GHz
- Transition frequency $f_{\rm T}$ = 25 GHz
- Gold metallization for high reliability
- SIEGET ® 25 GHz fT Line
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

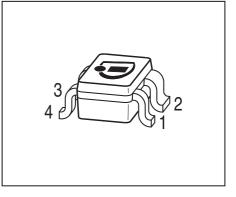
Туре	Marking	Pin Configuration					Package	
BFP420	AMs	1=B	2=E	3=C	4=E	-	-	SOT343

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V _{CEO}		V
<i>T</i> _A > 0 °C		4.5	
$T_{A} \leq 0 \ ^{\circ}C$		4.1	
Collector-emitter voltage	V _{CES}	15	
Collector-base voltage	V _{CBO}	15	
Emitter-base voltage	V _{EBO}	1.5	
Collector current	I _C	35	mA
Base current	I _B	3	
Total power dissipation ²⁾	P _{tot}	160	mW
<i>T</i> _S ≤ 107 °C			
Junction temperature	T _i	150	°C
Ambient temperature	T _A	-65 150	
Storage temperature	T _{sta}	-65 150	

¹Pb-containing package may be available upon special request

 $^2{\cal T}_S$ is measured on the collector lead at the soldering point to the pcb





Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	≤ 260	K/W

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.]
DC Characteristics			•	•	•
Collector-emitter breakdown voltage	V _{(BR)CEO}	4.5	5	-	V
<i>I</i> _C = 1 mA, <i>I</i> _B = 0					
Collector-emitter cutoff current	I _{CES}	-	-	10	μA
$V_{\rm CE}$ = 15 V, $V_{\rm BE}$ = 0					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{\rm CB}$ = 5 V, $I_{\rm E}$ = 0					
Emitter-base cutoff current	I _{EBO}	-	-	3	μA
$V_{\rm EB}$ = 0.5 V, $I_{\rm C}$ = 0					
DC current gain	h _{FE}	60	95	130	-
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 4 V, pulse measured					

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance



Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random samplin	g)	1	1	1	1
Transition frequency	f _T	18	25	-	GHz
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 3 V, f = 2 GHz					
Collector-base capacitance	C _{cb}	-	0.15	0.3	pF
$V_{\rm CB}$ = 2 V, f = 1 MHz, $V_{\rm BE}$ = 0 ,					
emitter grounded					
Collector emitter capacitance	C _{ce}	-	0.37	-	
$V_{CE} = 2 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
base grounded					
Emitter-base capacitance	C _{eb}	-	0.55	-	
$V_{\rm EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{\rm CB} = 0$,					
collector grounded					
Noise figure	F	-	1.1	-	dB
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 2 V, f = 1.8 GHz, $Z_{\rm S}$ = $Z_{\rm Sopt}$					
Power gain, maximum stable ¹⁾	G _{ms}	-	21	-	dB
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 2 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{\rm L} = Z_{\rm Lopt}$, $f = 1.8 {\rm GHz}$					
Insertion power gain	S ₂₁ ²	14	17	-	
V _{CE} = 2 V, <i>I</i> _C = 20 mA, <i>f</i> = 1.8 GHz,					
$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$					
Third order intercept point at output ²⁾	IP ₃	-	22	-	dBm
V _{CE} = 2 V, <i>I</i> _C = 20 mA, <i>f</i> = 1.8 GHz,					
$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$					
1dB Compression point at output	P _{-1dB}	-	12	-]
$I_{\rm C}$ = 20 mA, $V_{\rm CE}$ = 2 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω ,					
<i>f</i> = 1.8 GHz					

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified

 ${}^{1}G_{\rm ms} = |S_{21} / S_{12}|$

 2 IP3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.1 MHz to 6 GHz



Simulation Data

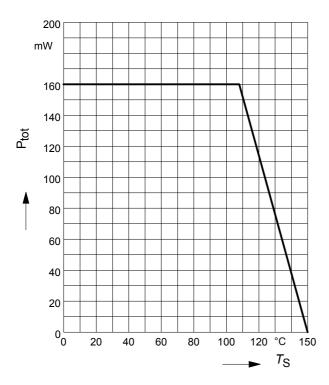
For SPICE-model as well as for S-parameters including noise parameters refer to our internet website: www.infineon.com/rf.models. Please consult our website and download the latest version before actually starting your design. The simulation data have been generated and verified up to 10 GHz using typical devices. The BFP420 nonlinear SPICE-model reflects the typical DC- and RF-device performance with high accuracy.



BFP420

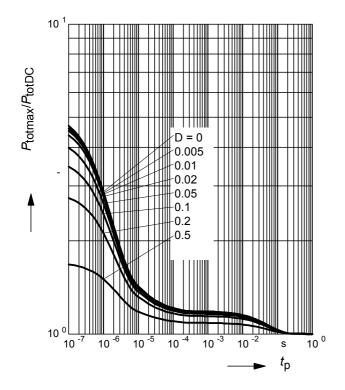
Total power dissipation $P_{tot} = f(T_S)$

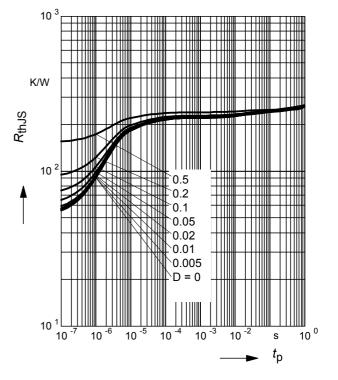
Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$



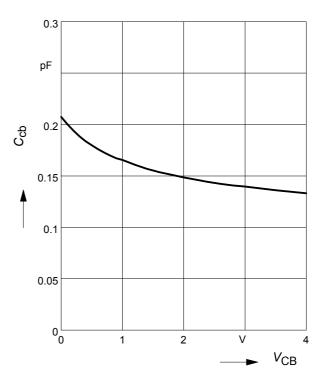
Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$





Collector-base capacitance C_{cb} = $f(V_{CB})$ f = 1MHz



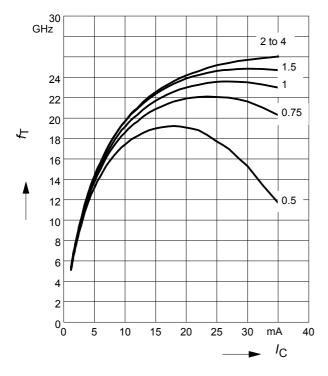
2009-12-02



Transition frequency $f_{T} = f(I_{C})$

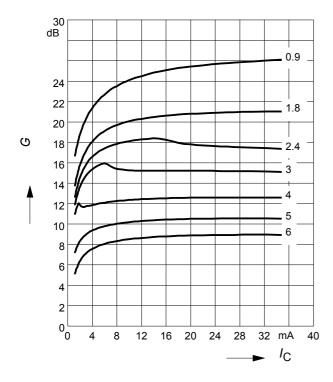
f = 2 GHz

 V_{CE} = parameter in V

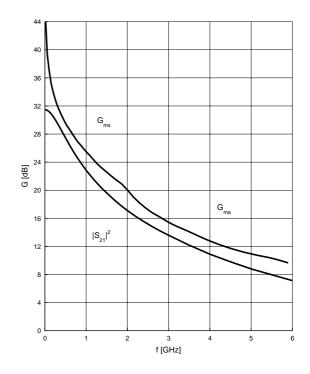


Power gain
$$G_{ma}$$
, $G_{ms} = f(I_C)$
 $V_{CE} = 2V$

f = parameter in GHz

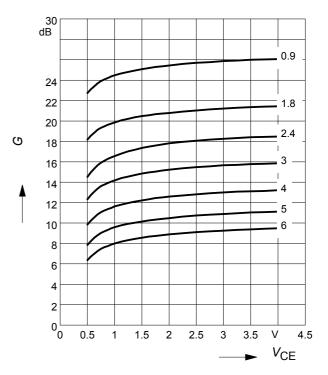


Power gain G_{ma} , G_{ms} , $|S_{21}|^2 = f(f)$ $V_{CE} = 2 \text{ V}$, $I_C = 20 \text{ mA}$



Power gain G_{ma} , $G_{ms} = f (V_{CE})$ $I_{C} = 20 \text{ mA}$

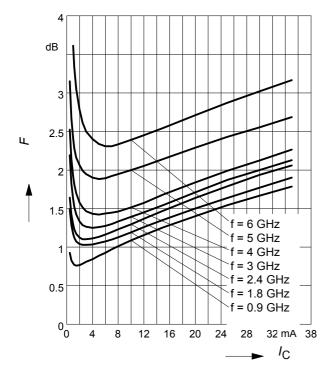
f = parameter in GHz

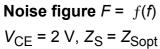


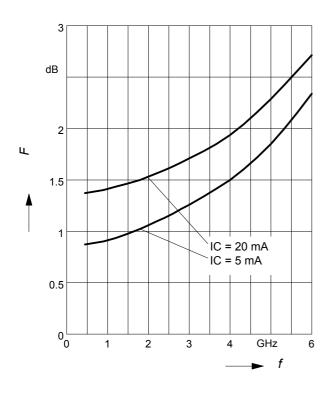
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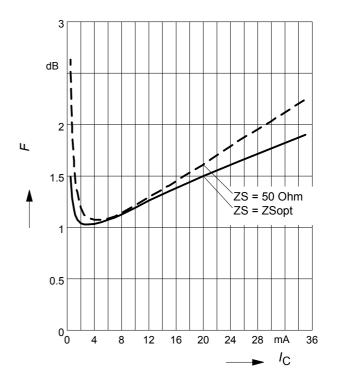
Noise figure $F = f(I_C)$ $V_{CE} = 2 V, Z_S = Z_{Sopt}$





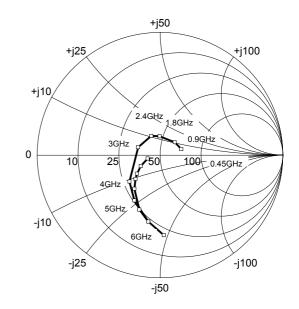


Noise figure $F = f(I_C)$ $V_{CE} = 2 \text{ V}, f = 1.8 \text{ GHz}$

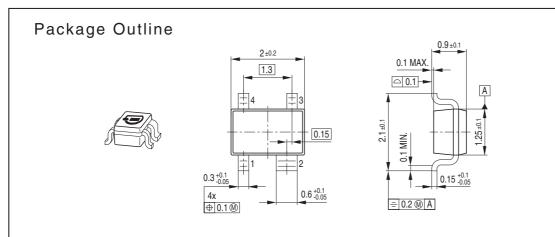


Source impedance for min. noise figure vs. frequency

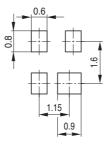
 $V_{\rm CE}$ = 2 V, $I_{\rm C}$ = 5 mA / 20 mA



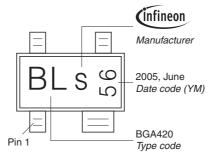




Foot Print

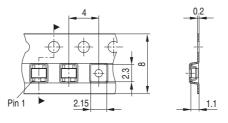


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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